

Amendments to the Claims:

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Presently Amended) A laminated flip-chip interconnect package comprising a substrate having a chip attach surface and a an opposing board attach surface that define contact pads for attachment to corresponding pads on the chip and board, wherein the ~~substrate~~ board attach surface comprises contact pads opposite a chip attach location and regions adjacent the chip attach location on the chip attach surface except at least one solid plane covering the area of the board attach surface, said area being opposite a chip attach surface region near adjacent a at least one chip corner of a chip attach location, and said solid plane board attach surface comprising a dielectric material.

2. (Presently Amended) A laminated flip-chip interconnect package according to claim 1 wherein said dielectric material is covered with a layer of material selected from a ~~soldermask~~ solder mask and a coverlay material.

3. (Original) A laminated flip-chip interconnect package according to claim 2 wherein said layer of material is selected from the group consisting of polyimide, polytetrafluoroethylene, and expanded polytetrafluoroethylene impregnated with cyanate ester and epoxy.

4. (Presently Amended) A laminated flip-chip interconnect package comprising a substrate having a chip attach surface and a an opposing board attach surface that define contact pads for attachment to corresponding pads on the chip and board, wherein the ~~substrate~~ board attach surface comprises at least one solid plane ~~covering the area, said area being opposite a~~ chip attach surface region near adjacent at least one the chip corner[[s]] of a chip attach location, and said board attach surface solid plane comprising a metal.

5. (Original) A laminated flip-chip interconnect package according to claim 4 wherein said metal is selected from the group consisting of copper, silver, gold and aluminum.

6. (Presently Amended) A laminated flip-chip interconnect package according to claim 4 wherein said metal is covered with a layer of material selected from a ~~soldermask~~ solder mask and a coverlay material.

7. (Original) A laminated flip-chip interconnect package according to claim 6 wherein said layer of material is selected from the group consisting of polyimide, polytetrafluoroethylene, and expanded polytetrafluoroethylene impregnated with cyanate ester and epoxy.

8. (Presently Amended) A laminate flip-chip interconnect package according to claim 4 wherein said ~~soldermask~~ solder mask has a plurality of openings defining ball grid array pads.